Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **1A**
2. **2A**
3. **2B**
4. **2C**
5. **2D**
6. **2Y**
7. **GND**
8. **1Y**
9. **1D**
10. **1E**
11. **1F**
12. **1B**
13. **1C**
14. **VCC**

**.041”**

**1 14 13**

**2**

**3**

**4**

**5**

**.6 7 8**

**12**

**11**

**10**

**9**

**1 5**

**MASK**

**REF**

**5 7**

**.043”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004 x .004”**

**Backside Potential: GND**

**Mask Ref: 1557**

**APPROVED BY: DK DIE SIZE .041” X .043” DATE: 4/17/20**

**MFG: TEXAS INSTRUMENTS THICKNESS .025” P/N: 54LS51**

**DG 10.1.2**

#### Rev B, 7/1